



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2013-07-04
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Giuseppe Vitali Palma	Representative Title	AMS & IPD Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	HYXP*V876AAJ	A	Z6HA	2013-07-04
Amount	UoM	Unit type	ST ECOPACK Grade	
6.886	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
QFN	2,2,0.75	8	No lead	
Comment	Package: MLPD/DFN 2x2x0.75 8L PITCH 0.5			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList :REACH-19 December 2012				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	HYXP*V876AAJ					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Silicon die	Other inorganic materials	0.33	mg	SUPPLIER	Die	Si	7440-21-3		0.33	mg	1000000	47923
Leadframe	Copper and its alloy	1.502	mg	SUPPLIER	Alloy	Copper	7440-50-8		1.445	mg	962051	209846
Leadframe			mg	SUPPLIER	Alloy	Iron	7439-89-6		0.034	mg	22636	4938
Leadframe			mg	SUPPLIER	Alloy	Phosphorus	7723-14-0		0.001	mg	666	145
Leadframe			mg	SUPPLIER	Alloy	Zinc	7440-66-6		0.002	mg	1332	290
Leadframe			mg	SUPPLIER	Metallization	Nickel	7440-02-0		0.017	mg	11318	2469
Leadframe			mg	SUPPLIER	Metallization	Palladium	7440-05-3		0.002	mg	1332	290
Leadframe			mg	SUPPLIER	Metallization	Gold	7440-57-5		0.001	mg	666	145
Die attach	Other organic materials	0.155	mg	SUPPLIER	Epoxy	Aluminium oxide	1344-28-1		0.046	mg	296774	6680
Die attach			mg	SUPPLIER	Epoxy	Diethylene glycol monoethyl ether acetate	112-15-2		0.062	mg	400000	9004
Die attach			mg	SUPPLIER	Epoxy	Epoxy resin	25068-38-6		0.011	mg	70968	1597
Die attach			mg	SUPPLIER	Epoxy	Epoxy resin	Proprietary		0.031	mg	200000	4502
Die attach			mg	SUPPLIER	Epoxy	Aromatic amine	Proprietary		0.005	mg	32258	726
Bonding wire	Other inorganic materials	0.03	mg	SUPPLIER	Bonding Wire	Au	7440-57-5		0.03	mg	1000000	4357
Encapsulation	Other organic materials	4.869	mg	SUPPLIER	molding compound	Silica Fused	60676-86-0		4.554	mg	935305	661342
Encapsulation			mg	SUPPLIER	molding compound	Epoxy Resin	Proprietary		0.15	mg	30807	21783
Encapsulation			mg	SUPPLIER	molding compound	Phenol Resin	Proprietary		0.15	mg	30807	21783
Encapsulation			mg	SUPPLIER	molding compound	Carbon Black	1333-86-4		0.015	mg	3081	2178